

Global Microelectronics Packaging Adhesives Supply, Demand and Key Producers, 2026-2032

<https://marketpublishers.com/r/GBE67AB31670EN.html>

Date: August 2026

Pages: 166

Price: US\$ 4,480.00 (Single User License)

ID: GBE67AB31670EN

Abstracts

The global Microelectronics Packaging Adhesives market size is expected to reach \$ 5102 million by 2032, rising at a market growth of 8.2% CAGR during the forecast period (2026-2032).

Microelectronics Packaging Adhesives are high-performance functional adhesive materials used in the packaging, assembly, interconnection and protection of microelectronic devices. They are mainly applied in semiconductor packaging, chip-scale packaging, sensor packaging, optical modules, RF devices, power devices and high-reliability electronic modules. These products are commonly supplied in liquid, paste, film or preformed formats. Major product types include underfill adhesives, die attach adhesives, die attach films, non-conductive pastes, non-conductive films, electrically conductive adhesives, thermally conductive adhesives, encapsulation adhesives, glob top encapsulants, lid attach adhesives, corner fill adhesives and edge bond adhesives.

Microelectronics Packaging Adhesives require high purity, low ionic contamination, low outgassing, low stress, low warpage, high bonding strength, moisture resistance, thermal cycling resistance, dimensional stability and compatibility with automated semiconductor packaging processes. Major production regions include Japan, the United States, Germany, China, South Korea and Taiwan, China. Representative applications include flip chip packaging, wire bond packaging, chip-scale packaging, ball grid array packaging, system-in-package, fan-out packaging, camera modules, image sensors, MEMS, automotive electronics, AI chips and high-performance computing chip packaging.

In 2025, global Microelectronics Packaging Adhesives production reached

approximately 22,500-25,500 tons. The product mix was mainly composed of underfill adhesives, die attach adhesives, die attach films, electrically conductive adhesives, thermally conductive adhesives, encapsulation adhesives and package reinforcement adhesives. Driven by demand from advanced packaging, AI chips, automotive electronics, image sensors and high-reliability power devices, the average FOB price was approximately USD 112-124 per kilogram. Standard package reinforcement materials and conventional die attach adhesives were priced below the industry average, while low-stress underfills, silver-filled conductive adhesives, high-thermal-conductivity die attach adhesives, non-conductive films and customized adhesives for advanced packaging carried a significant premium.

The global Microelectronics Packaging Adhesives market is shifting from conventional auxiliary packaging materials toward high-reliability, high-precision and multifunctional packaging materials. The rapid growth of AI servers, high-performance computing, advanced packaging, automotive electronics, image sensors, RF devices and power semiconductors is pushing package architectures toward larger die sizes, multi-die integration, finer interconnect pitches and higher thermal density. This trend is driving upgrades in underfills, die attach adhesives, non-conductive films, thermal adhesives and package reinforcement adhesives. For material suppliers, product value is no longer defined only by bonding strength, but also by low stress, low warpage, high thermal conductivity, low ionic contamination, process stability and long-term reliability.

Market challenges include long customer qualification cycles, high technical entry barriers, formulation iteration risk, price volatility in high-purity resins and functional fillers, and cyclical demand from semiconductors and consumer electronics. Advanced packaging and automotive-grade applications typically require long-term reliability data, strict process-window validation and stable global supply capability, creating strong customer stickiness for leading material suppliers. Companies with advanced packaging customer access, high-purity manufacturing capabilities, local technical service networks and multi-product platform portfolios are expected to be more competitive. Asia Pacific remains the primary production and consumption hub, while Japanese, U.S. and German suppliers maintain advantages in high-end formulations and long qualification histories, and Chinese suppliers continue to improve in domestic substitution, mid-to-high-end package adoption and fast technical response.

This report studies the global Microelectronics Packaging Adhesives production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for

Microelectronics Packaging Adhesives and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of Microelectronics Packaging Adhesives that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global Microelectronics Packaging Adhesives total production and demand, 2021-2032, (Tons)

Global Microelectronics Packaging Adhesives total production value, 2021-2032, (USD Million)

Global Microelectronics Packaging Adhesives production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (Tons), (based on production site)

Global Microelectronics Packaging Adhesives consumption by region & country, CAGR, 2021-2032 & (Tons)

U.S. VS China: Microelectronics Packaging Adhesives domestic production, consumption, key domestic manufacturers and share

Global Microelectronics Packaging Adhesives production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (Tons)

Global Microelectronics Packaging Adhesives production by Type, production, value, CAGR, 2021-2032, (USD Million) & (Tons)

Global Microelectronics Packaging Adhesives production by Application, production, value, CAGR, 2021-2032, (USD Million) & (Tons)

This report profiles key players in the global Microelectronics Packaging Adhesives market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Henkel AG & Co. KGaA, NAMICS Corporation, Resonac Corporation, Panasonic Industry Co., Ltd., Shin-Etsu Chemical Co., Ltd., Nagase ChemteX Corporation, ThreeBond Co., Ltd., Nitto Denko Corporation, LINTEC Corporation, LG Chem, Ltd., etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Microelectronics Packaging Adhesives market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), volume (production, consumption) & (Tons) and average price (US\$/Ton) by manufacturer, by Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global Microelectronics Packaging Adhesives Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global Microelectronics Packaging Adhesives Market, Segmentation by Type:

Underfill and Reinforcement Adhesives

Die Attach Adhesives

Encapsulation and Potting Adhesives

Conductive and Thermal Adhesives

Others

Global Microelectronics Packaging Adhesives Market, Segmentation by Material Chemistry:

Epoxy Adhesives

Silicone Adhesives

Acrylic and Urethane Adhesives

Polyimide and Hybrid Adhesives

Global Microelectronics Packaging Adhesives Market, Segmentation by Product Form:

Liquid Adhesives

Paste Adhesives

Film Adhesives

Others

Global Microelectronics Packaging Adhesives Market, Segmentation by End Use Industry:

Consumer Electronics

Computing and Communication

Automotive Electronics

Industrial and Medical Electronics

Global Microelectronics Packaging Adhesives Market, Segmentation by Application:

Semiconductor Packaging

Sensor and Optical Module Packaging

Power Electronics Packaging

Radio Frequency and Communication Module Packaging

Companies Profiled:

Henkel AG & Co. KGaA

NAMICS Corporation

Resonac Corporation

Panasonic Industry Co., Ltd.

Shin-Etsu Chemical Co., Ltd.

Nagase ChemteX Corporation

ThreeBond Co., Ltd.

Nitto Denko Corporation

LINTEC Corporation

LG Chem, Ltd.

Won Chemical Co., Ltd.

DELO Industrial Adhesives

Hoenle Adhesives GmbH

Protavic International

Element Solutions Inc.?MacDermid Alpha Electronics Solutions?

Parker Hannifin Corporation?Parker LORD?

Meridian Adhesives Group?EPO-TEK?

Master Bond Inc.

Zymet, Inc.

AI Technology, Inc.

YINCAE Advanced Materials, LLC

Key Questions Answered:

1. How big is the global Microelectronics Packaging Adhesives market?
2. What is the demand of the global Microelectronics Packaging Adhesives market?
3. What is the year over year growth of the global Microelectronics Packaging Adhesives market?
4. What is the production and production value of the global Microelectronics Packaging Adhesives market?
5. Who are the key producers in the global Microelectronics Packaging Adhesives market?
6. What are the growth factors driving the market demand?

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